

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	948	(dissolved adj oxygen) and (semiconductor or resist or photoresist)	USPAT	OR	OFF	2005/05/02 11:03
L2	283	1 and (fluorine or fluoric or hydrofluoric or fluoride)	USPAT	OR	OFF	2005/05/02 12:41
L3	283	1 and (fluorine or fluoric or hydrofluoric or fluoride)	USPAT	OR	OFF	2005/05/02 14:26
L4	16	((("5314725") or ("6331490") or ("6664197") or ("5424252") or ("6417112") or ("6638899") or ("6165912") or ("4112044") or ("6323169") or ("6767689") or ("5698503") or ("5308745") or ("5622919") or ("6368421") or ("6261745") or ("6554912"))).PN.	USPAT	OR	OFF	2005/05/02 16:01
L5	0	(us-20020032280-\$.did.	USPAT	OR	OFF	2005/05/02 16:01
L6	1	(us-20020032280-\$.did.	US-PGPUB; USPAT	OR	OFF	2005/05/02 16:02
L7	1	("20020032280").PN.	US-PGPUB; USPAT	OR	OFF	2005/05/02 16:02
L8	7	((("5314725") or ("5698503") or ("6261745") or ("6323169") or ("6368421") or ("6554912") or ("6638899"))).PN.	USPAT	OR	OFF	2005/05/02 16:24
L9	158424	(solution or composition) and (fluorine or fluoride or fluoro or fluoric or hydrofluoric) not (peroxide or peroxygen)	USPAT	OR	OFF	2005/05/02 16:24

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Serial Number:  
10601659  
Pgpub Number:  
0

Keywords:  
code;ikemoto;kazuto;february;resist;resist  
stripping;stripping;liquid;containing;fluorine;compound;abstract;concentration;disso  
lved;dissolved oxygen;oxygen;ppm;residues;removed;substrate;copper;copper  
alloy;alloy;causing;corrosion;inventors;tokyo;ohito;masaru;correspondence;

Class list:  
510/176;510/175;134/3;134/2;510/255;134/1.3;134/41;510/499;134/42;252/79.4;

Int Class list:  
C11D 007/50;B08B 003/08;C11D 007/32;C23G 001/02;H01L 021/302;H01L 021/306;C11D  
007/26;C11D 007/08;B08B 003/04;H01L 021/461;

Special Keywords:  
strip;stripping;stripping photoresists;photoresist;DMSO;glycol ether;dissolved  
oxygen;

Negative Keywords:  
dishwashing;CMP;polishing;peroxide;hydrogen peroxide;peroxygen;

Features:  
feature#1(w=200);fluorine compound;hydrofluoric;fluoride;fluorine;  
feature#2(w=200);dissolved oxygen;deionized water;DI water;ultrapure water;  
feature#3(w=100);preferred solvent;ethylene glycol monoethyl ether;ethylene glycol  
monobutyl ether;diethylene glycol monomethyl ether;diethylene glycol monoethyl  
ether;diethylene glycol monobutyl ether;triethylene glycol;triethylene glycol  
monomethyl ether;triethylene glycol monoethyl ether;triethylene glycol monopropyl  
ether;triethylene glycol monobutyl ether;triethylene glycol dimethyl ether;propylene  
glycol monomethyl ether;propylene glycol monoethyl ether;propylene glycol monobutyl  
ether;propylene glycol monomethyl ether;propylene glycol monoethyl  
ether;propylene glycol monobutyl ether;diethylene glycol dimethyl  
ether;diethylene glycol dimethyl  
ether;formamide;monomethylformamide;dimethylformamide;monoethylformamide;diethylform  
amide;acetamide;monomethylacetamide;dimethylacetamide;monoethylacetamide;diethylacet  
amide;N-methylpyrrolidone;N-ethylpyrrolidone;N-methylcaprolactam;methyl  
alcohol;ethyl alcohol;isopropanol;ethylene glycol;propylene glycol;dimethyl  
sulfoxide;dimethylsulfone;diethyl sulfone;bis(2-hydroxyethyl) sulfone;tetramethylene  
sulfone;1,3-dimethyl-2-imidazolidinone;1,3-diethyl-2-imidazolidinone;1,3-diisopropyl  
-2-imidazolidinone;.gamma.-butyrolactone;.delta.-valerolactone;aminoethanol;diethano  
lamine;triethanolamine;isopropanolamine;1-amino-3-propanol;diisopropanolamine;triiso  
propanolamine;dimethylaminoethanol;N-methylaminoethanol;diethylaminoethanol;aminoeth  
oxyethanol;ethylenediamine;diethylenetriamine;triethylenetetramine;tetraethylenepent  
amine;  
feature#4(w=600);preferred fluorinated compound;ammonium fluoride;acid ammonium  
fluoride;hydrofluoric acid;hydrofluoric;fluoric;  
feature#5(w=200);method for removing resists;photoresist;resist;  
feature#6(w=100);copper and/or;copper alloy;copper;copper alloy;copper oxide;